

## DESCRIPTION:

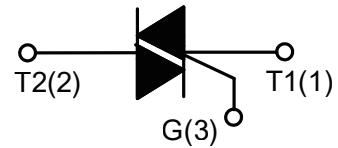
The BTA08-800C SCR series with the parallel resistor between Gate and Cathode are especially recommended for use on straight hair, igniter, anion generator, etc.



TO-263      TO-252

## MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	8	A
$V_{DRM}/V_{RRM}$	600/800/1200	V



## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Storage junction temperature range	$T_{stg}$	-40 - 150	°C
Operating junction temperature range	$T_j$	-40 - 125	°C
Repetitive peak off-state voltage ( $T_j=25^\circ\text{C}$ )	$V_{DRM}$	600/800/1200	V
Repetitive peak reverse voltage ( $T_j=25^\circ\text{C}$ )	$V_{RRM}$	600/800/1200	V
Non repetitive surge peak Off-state voltage	$V_{DSM}$	$V_{DRM} + 100$	V
Non repetitive peak reverse voltage	$V_{RSM}$	$V_{RRM} + 100$	V
RMS on-state current ( $T_c=90^\circ\text{C}$ )	$I_{T(RMS)}$	8	A
TO-252 ( $T_c=100^\circ\text{C}$ )			
Non repetitive surge peak on-state current (full cycle, $F=50\text{Hz}$ )	$I_{TSM}$	80	A
$I^2t$ value for fusing ( $t_p=10\text{ms}$ )	$I^2t$	32	$\text{A}^2\text{s}$
Critical rate of rise of on-state current ( $I_G=2 \times I_{GT}$ )	$dI/dt$	50	$\text{A}/\mu\text{s}$
Peak gate current	$I_{GM}$	4	A
Average gate power dissipation	$P_{G(AV)}$	1	W
Peak gate power	$P_{GM}$	5	W

**ELECTRICAL CHARACTERISTICS (T<sub>j</sub>=25°C unless otherwise specified)**

3 Quadrants

<b>Symbol</b>	<b>Test Condition</b>	<b>Quadrant</b>		<b>Value</b>				<b>Unit</b>
				<b>TW</b>	<b>SW</b>	<b>CW</b>	<b>BW</b>	
I <sub>GT</sub>	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	I - II - III	MAX	5	10	35	50	mA
V <sub>GT</sub>		I - II - III	MAX	1.5				V
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> T <sub>j</sub> =125°C R <sub>L</sub> =3.3KΩ	I - II - III	MIN	0.2				V
I <sub>L</sub>	I <sub>G</sub> =1.2I <sub>GT</sub>	I - III	MAX	20	25	50	70	mA
		II		25	35	70	90	
I <sub>H</sub>	I <sub>TM</sub> =100mA		MAX	15	20	40	60	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125°C		MIN	50	200	500	1000	V/μs

4 Quadrants

<b>Symbol</b>	<b>Test Condition</b>	<b>Quadrant</b>		<b>Value</b>		<b>Unit</b>	
				<b>C</b>	<b>B</b>		
I <sub>GT</sub>	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	I - II - III	MAX	25	50	mA	
		IV		50	70		
V <sub>GT</sub>		ALL	MAX	1.5			
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> T <sub>j</sub> =125°C R <sub>L</sub> =3.3KΩ	ALL	MIN	0.2			
I <sub>L</sub>	I <sub>G</sub> =1.2I <sub>GT</sub>	I - III - IV	MAX	50	70	mA	
		II		70	90		
I <sub>H</sub>	I <sub>TM</sub> =200mA		MAX	40	60	mA	
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125°C		MIN	200	500	V/μs	

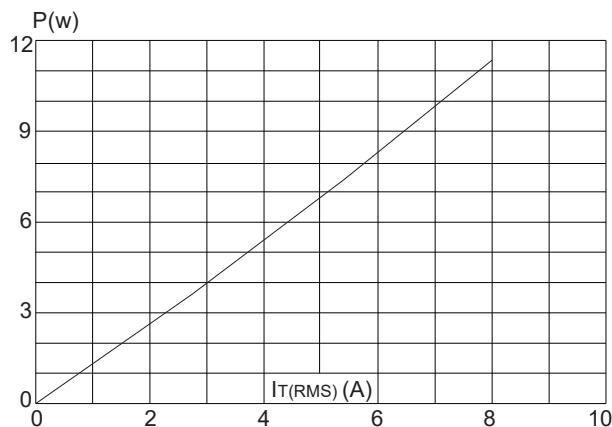
**STATIC CHARACTERISTICS**

<b>Symbol</b>	<b>Parameter</b>		<b>Value(MAX)</b>	<b>Unit</b>
V <sub>TM</sub>	I <sub>TM</sub> =11A tp=380μs		T <sub>j</sub> =25°C	1.5
I <sub>DRM</sub>	V <sub>D</sub> =V <sub>DRM</sub> V <sub>R</sub> =V <sub>RRM</sub>		T <sub>j</sub> =25°C	5
I <sub>RRM</sub>			T <sub>j</sub> =125°C	1

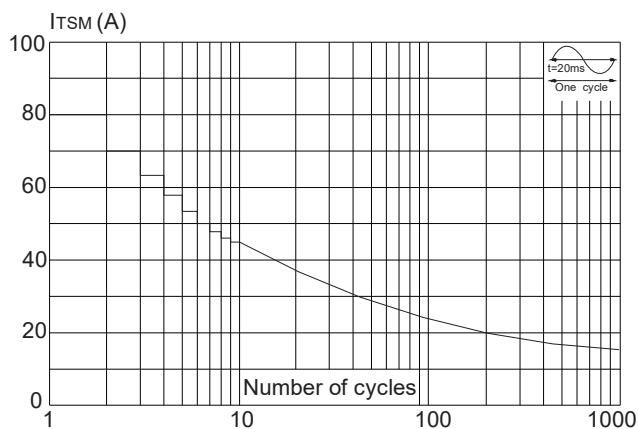
## THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	junction to case(AC)	TO-263	3.0	°C/W
		TO-252 2.1		
$R_{th(j-a)}$	junction to ambient	TO-263	45	°C/W
		TO-252 70		

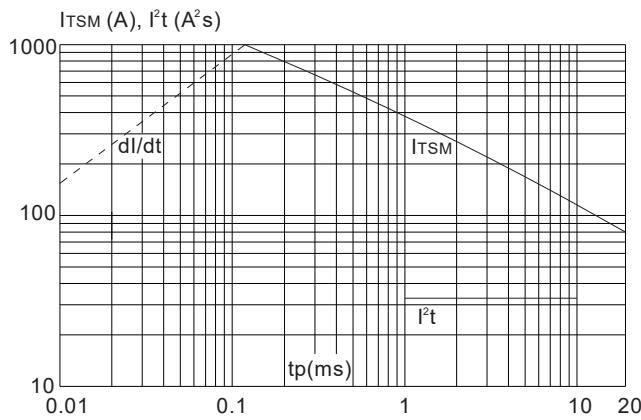
**FIG.1:** Maximum power dissipation versus RMS on-state current



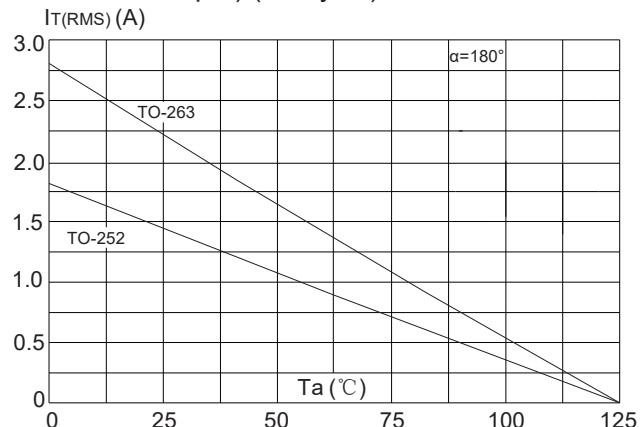
**FIG.3:** Surge peak on-state current versus number of cycles



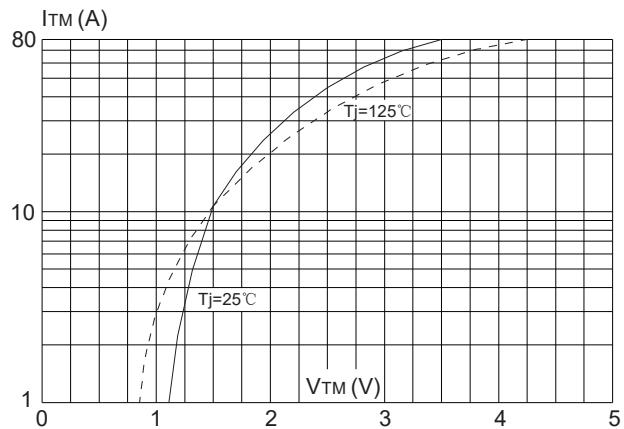
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 20\text{ms}$ , and corresponding value of  $I^2t$  ( $dI/dt < 50\text{A}/\mu\text{s}$ )



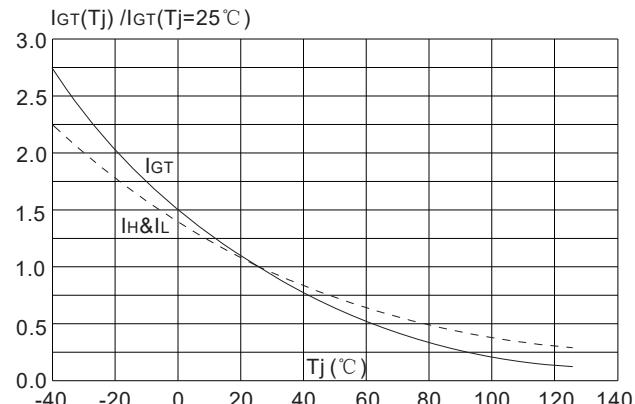
**FIG.2:** RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness:35 $\mu\text{m}$ ) (full cycle)



**FIG.4:** On-state characteristics (maximum values)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature



## SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ( $T_{s(\min)}$ )	+150°C
	-Temperature Max( $T_{s(\max)}$ )	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp ( $T_L$ )to peak)		3°C/sec. Max
$T_{s(\max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ ) (Liquidus)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_p$ )		8 min. Max
Do not exceed		+260°C

